

**SH251 Micro-power High Sensitivity Omni-polar Hall Effect Switch**

SH251 is a micro-power high sensitivity omni-polar Hall switch designed in advanced CMOS technology. The following are integrated on a single silicon chip: awake/sleep timing controller, Hall voltage generator, offset canceller, chopper stabilized small-signal amplifier, Schmitt trigger, CMOS output. Superior high-temperature performance is made possible through a dynamic offset cancellation that utilizes chopper-stabilization. Since SH251 is special made for low operation voltage (1.65V~) and micro-power (5 $\mu$ A typ.), it is suitable for battery-powered applications.

**Features**

- 1.65 to 3.5V for battery-powered application
- High sensitivity (3mT typ.)
- Stable temperature characteristics
- Low power consumption (5 $\mu$ A typ.)
- High ESD protection (HBM >  $\pm$ 4kV min)
- CMOS output
- Small size (QFN2020-3)

**Typical Applications**

- Solid-state switch
- Lid close sensor for battery powered devices
- Water meter
- Floating meter

**Ordering Information**

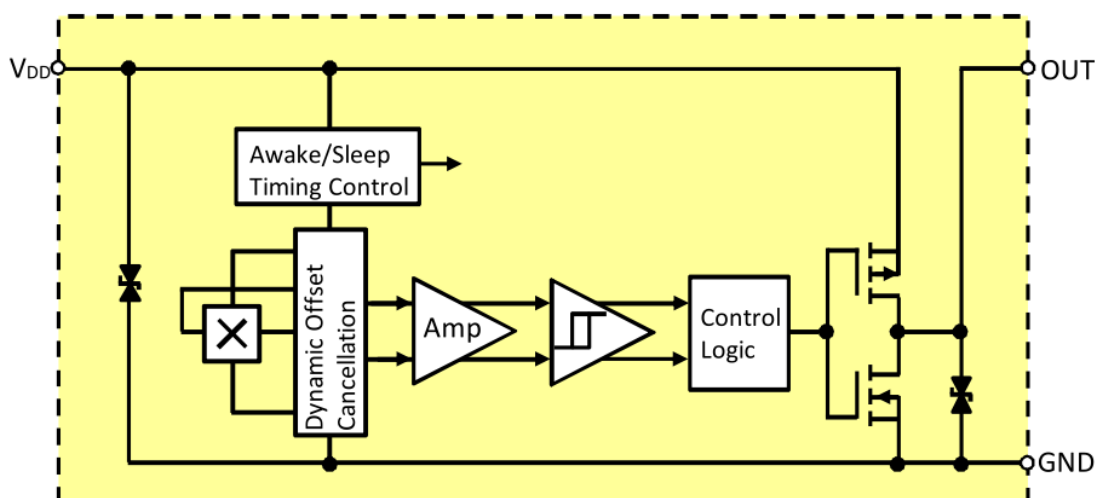
Model No.	Part No.	Temperature	Package	—	Packing
SH251EUA	SH251	E	UA		
SH251EST-TR	SH251	E	ST	—	TR
SH251ESQ-TR	SH251	E	SQ	—	TR

Legend:

Temperature Code: E (-40 $^{\circ}$ C~85 $^{\circ}$ C)

Package Code: UA (TO92S), ST (TSOT23), SQ (QFN2020-3)

Packing Code: Brank (Balk, 500pcs/Bag), TR (Tape & Reel, 3,000pcs/Reel)

**Functional Diagram**


**Absolute Maximum Ratings** ( $T_A=25^\circ\text{C}$ )

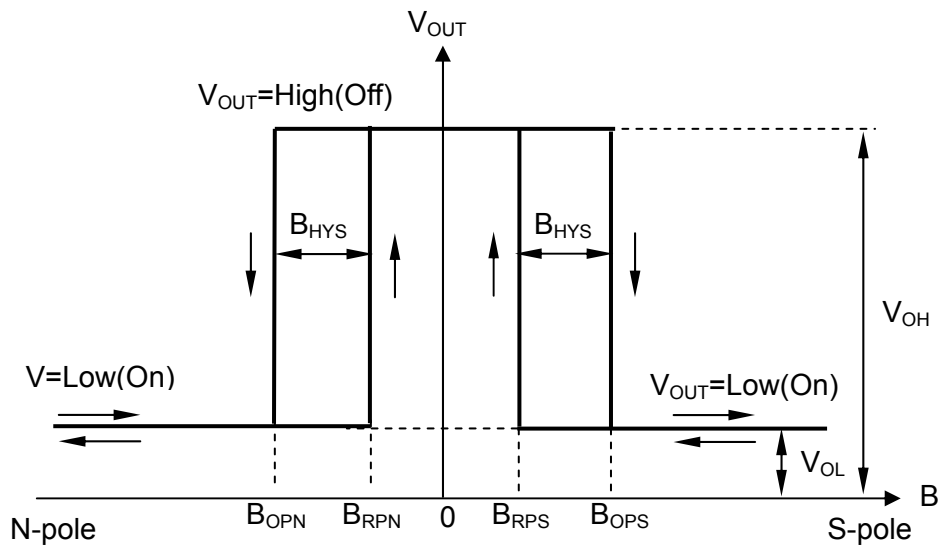
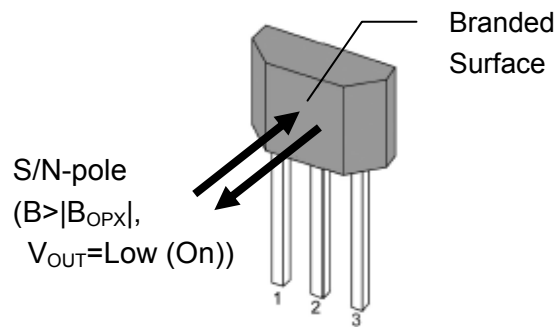
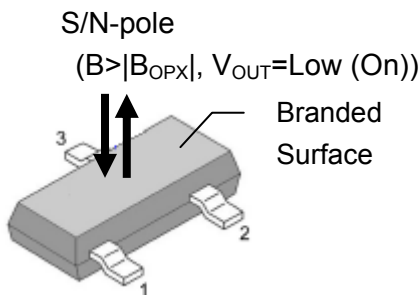
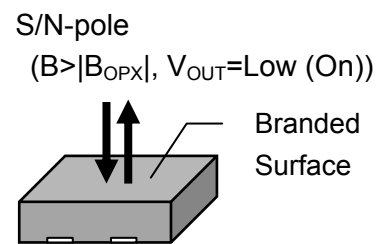
Parameter	Symbol	Value		Unit
		Min	Max	
Supply Voltage	$V_{DD}$	-0.3	4.5	V
Output Voltage	$V_{OUT}$	-0.3	4.5	V
Output Current	$I_{SINK}$	-	1	mA
Operating Temperature Range (E)	$T_A$	-40	85	$^\circ\text{C}$
Storage Temperature Range	$T_S$	-65	150	$^\circ\text{C}$
Maximum Junction Temperature	$T_J$		150	$^\circ\text{C}$
Power Dissipation (UA/ST/SQ)	$P_D$		606/400/230	mW

**Electrical Characteristics** ( $T_A=25^\circ\text{C}$ ,  $V_{DD}=1.8\text{V}$ )

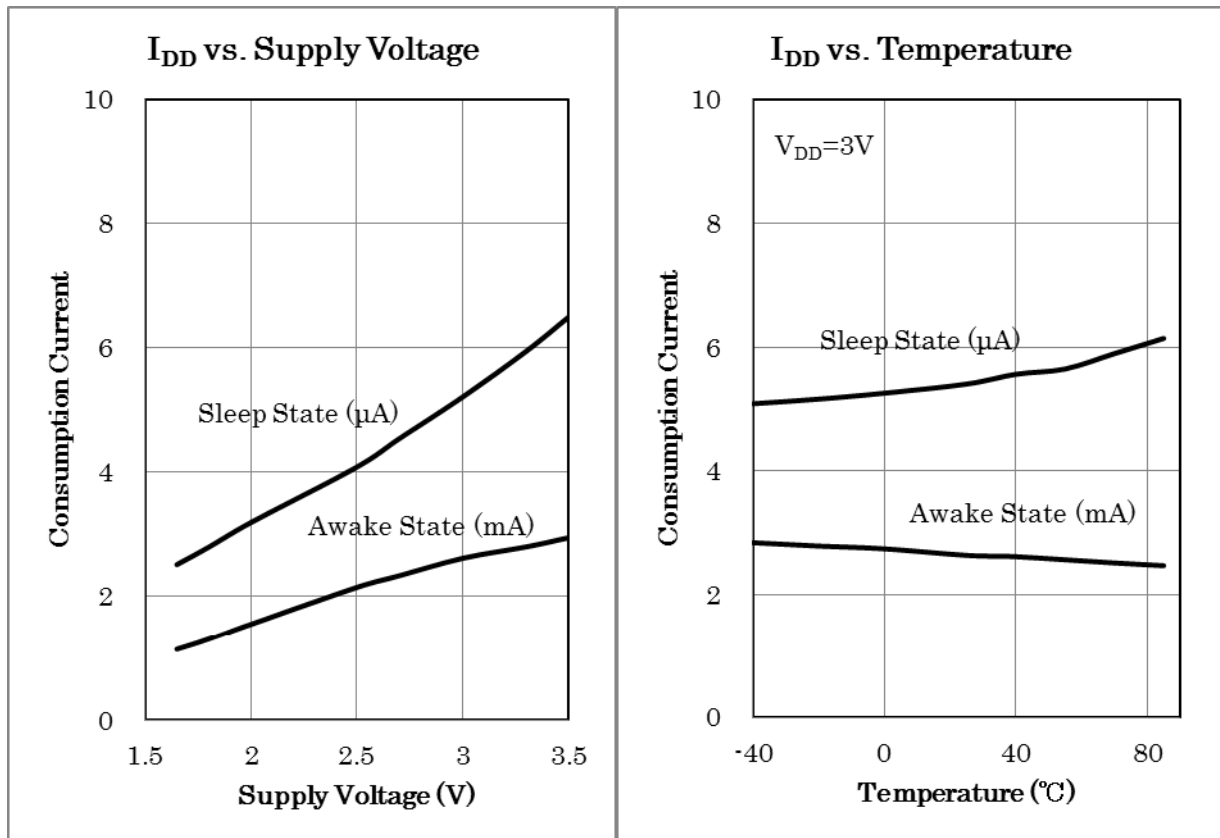
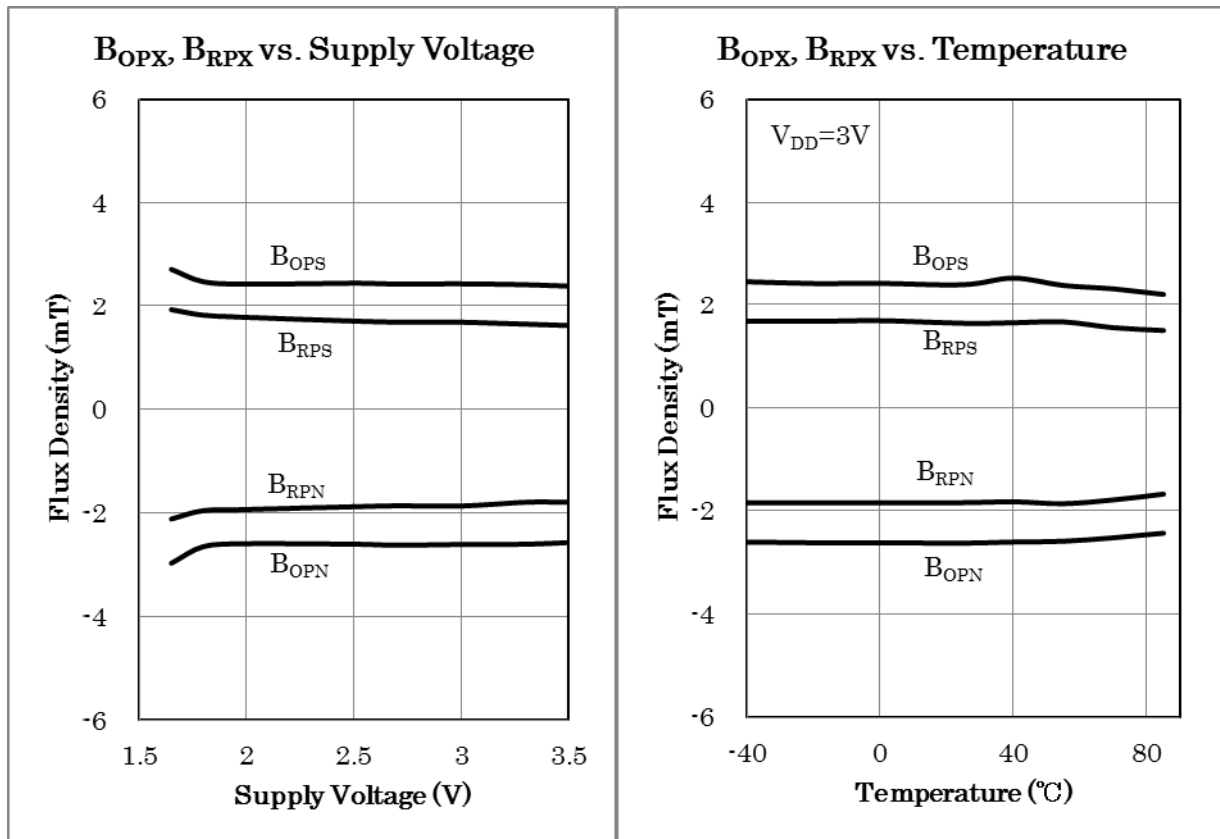
Parameter	Test Condition	Symbol	Value			Unit
			Min	Typ	Max	
Supply Voltage		$V_{DD}$	1.65	-	3.5	V
Consumption Current	Awake Mode	$I_{DD}$	-	1.4	3	mA
	Sleep Mode	$I_{DD}$		3.6	7	$\mu\text{A}$
	Average	$I_{DD}$	-	5	10	$\mu\text{A}$
Output High Voltage	$I_{OUT}=-0.5\text{mA}$ (Sink)	$V_{OH}$	$V_{DD}$ -0.2	-	-	V
Output Low Voltage	$I_{OUT}=0.5\text{mA}$ (Source)	$V_{OL}$	-	-	0.2	V
Awake Mode Time		$t_{AW}$	-	40	80	$\mu\text{s}$
Sleep Mode Time		$t_{SL}$	-	40	80	ms
Electro-Static Discharge	HBM		4	-	-	kV

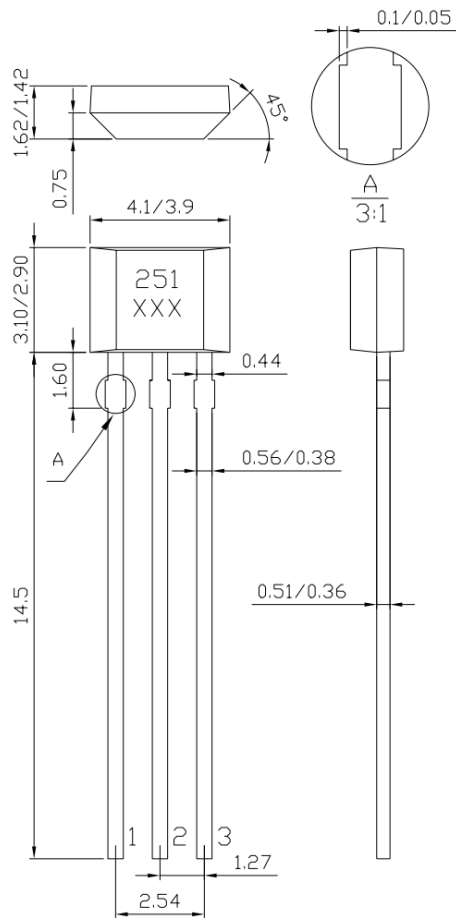
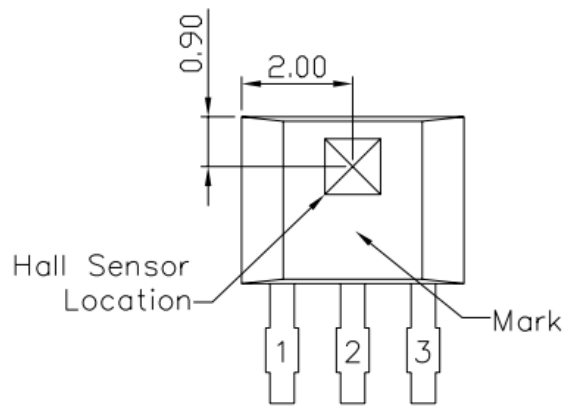
**Magnetic Characteristics** ( $T_A=25^\circ\text{C}$ ,  $V_{DD}=1.8\text{V}$ )

Parameter	Test Condition	Symbol	Value			Unit
			Min	Typ	Max	
Operate Point	S pole to branded side	$B_{OPS}$		3	5.5	mT
	N pole to branded side	$B_{OPN}$	-5.5	-3	-	mT
Release Point	S pole to branded side	$B_{RPS}$	1	2	-	mT
	N pole to branded side	$B_{RPN}$	-	-2	-1	mT
Hysteresis	$ B_{OPX} - B_{RPX} $	$B_{HYS}$	-	1	-	mT

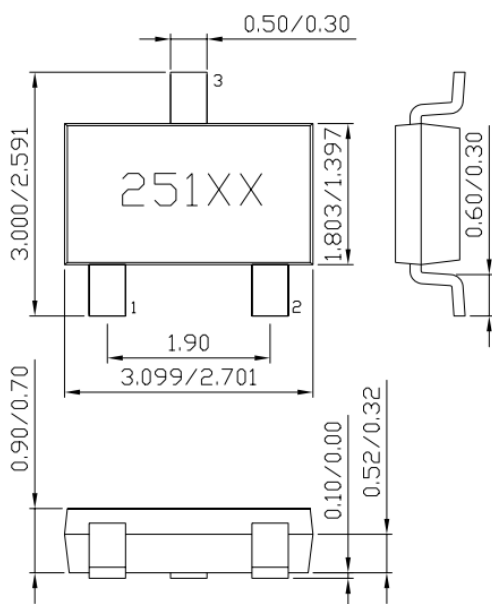
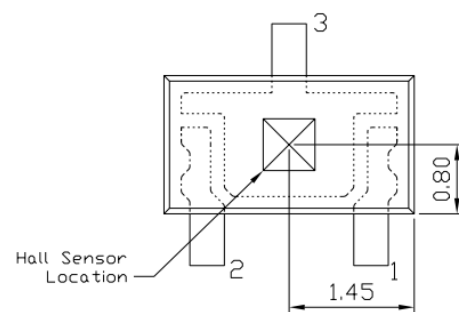

**Switching Characteristics**

**UA-package**

**ST-package**

**SQ-package**

Performance Graphs

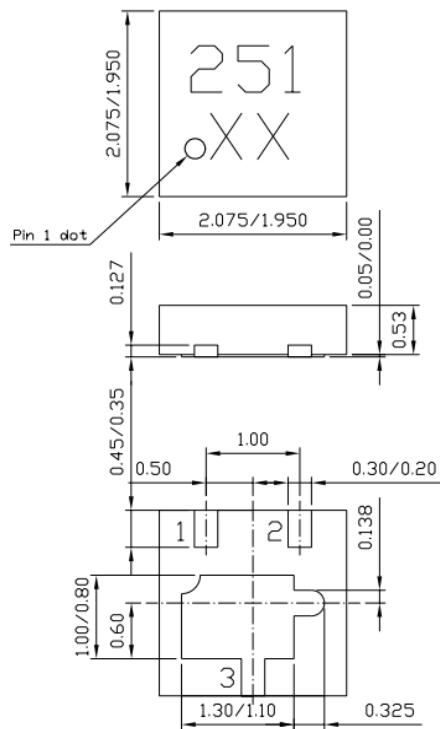
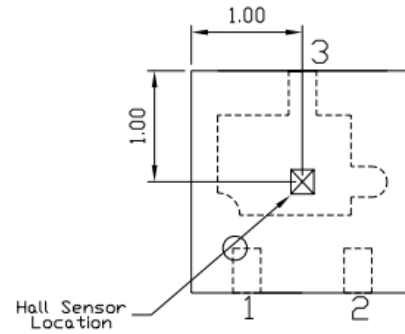


**Sensor Location, Package Dimension and Marking**
**UA-package: T092S**

**Hall sensor location**

**NOTES:**

1. Controlling dimension: mm
2. Leads must be free of flash and plating voids.
3. Do not bend leads within 1 mm of lead to package interface.
4. PINOUT:  
 Pin 1 V<sub>DD</sub>  
 Pin 2 GND  
 Pin 3 Output

**ST-package: TSOT23  
(Top View)**

**Hall sensor location  
(Bottom view)**

**NOTES:**

1. PINOUT:  
 Pin 1 V<sub>DD</sub>  
 Pin 2 Output  
 Pin 3 GND
2. Controlling dimension: mm;

**SQ-package: QFN2020-3**
**(Top View)**

**Hall sensor location**
**(Top View)**

**NOTES:**
**1. PINOUT:**

- Pin 1  $V_{DD}$
- Pin 2 Output
- Pin 3 GND

**2. Controlling dimension: mm;**
**3. Chip must be in PKG. center.**